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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Isao YOKOKAWA

Application No.: New U.S. Patent Application

Filed: June 28, 2006

Docket No.: 128503

For: METHOD FOR MEASURING AN AMOUNT OF STRAIN OF A BONDED
STRAINED WAFER

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please consider the following:

Amendments to the Claims as reflected in the listing of claims; and

Remarks.